

PCN Number:	20200807000.1A	PCN Date:	Nov. 19, 2020
Title:	Qualification of TIPI as an additional assembly site for select Devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Nov. 13, 2020	Estimated Sample Availability:	Date provided at sample request
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
<p>Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These new devices are highlighted and bolded in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only.</p> <p>Texas Instruments Incorporated is announcing the qualification of TIPI as an alternate Assembly site for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:</p>			
		NFME	UTAC
Mount Compound	SID# A-09 or SID# A-03	SID#PZ0076 or SID#PZ0013	4207123
Mold Compound	SID#R-13 or SID#R-17	SID#CZ0096	4222198
Bond wire, diameter	Au or Cu, 1.0mils	Au, 1.0mils	Cu, 0.96mils
Lead Frame Prep	non RLF	non RLF	RLF
Reason for Change:			
Supply continuity			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Anticipated impact on Material Declaration			
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp
Changes to product identification resulting from this PCN:			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
NFME	NFM	CHN	Economic Development Zone
UTAC	NS2	THA	Bangpakong, Chachoengsao

TIPI	PHI	PHL	Baguio City
-------------	------------	------------	--------------------

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



G4



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

UCC27517ADBVT	UCC27517ADBVR	UCC27518DBVR	UCC27519DBVR
UCC27517DBVT	UCC27517DBVR	UCC27518DBVT	UCC27519DBVT



TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UCC27517DBVR	QBS Process Reference: TPS2543QRTE	QBS Package Reference: TPS22810DBVR	QBS Package Reference: TPS2552DBVR
AC	Autoclave 121C	96 Hours	-	3/231/0	-	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	1/30/0	1/30/0
HAST	Biased HAST 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
HBM	ESD - HBM	3000 V	-	1/3/0	1/3/0	-
HBM	ESD - HBM - Q100	1000 V	-	1/3/0	-	-
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	-
HTOL	Life Test, 150C	408 Hours	-	3/231/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	3/231/0
HTSL	High Temp Storage Bake 175C	500 Hours	-	3/149/0	-	-
LU	Latch-up	-	-	1/6/0	1/6/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0	3/240/0	3/231/0
TC	Temperature Cycle, -65/150C	750 Cycles	-	-	-	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.